

Product Change Notification - KSRA-02YULJ618

Date:

24 Oct 2019

Product Category:

Linear Regulators

Affected CPNs:



Notification subject:

CCB 3452 Final Notice: Qualification of GTBF as a new assembly site for selected TC2117 device family available in 3L DDPAK package using CRM-1191AR-A die attach material.

Notification text:

PCN Status:

Final notification.

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of GTBF as a new assembly site for selected TC2117 device family available in 3L DDPAK package using CRM-1191AR-A die attach material

Pre Change:

Assembled at CARSEM using 84-3J die attach, CEL-9240HF10 molding compound and HCL-12S lead frame material.

Post Change:

Assembled at GTBF using CRM-1191AR-A die attach, EME-G600 molding compound and LY80 lead frame material.

Pre and Post Change Summary:

	Pre Change	Post Change				
Assembly Site	Carsem (M) SDN BHD	Great Team Backend Foundry				
	(CARM)	(Dong Guan) Ltd. (GTBF)				
Wire material	Au	Au				
Die attach material	84-3J	CRM-1191AR-A				
Molding compound	CEL-9240HF10	EME-G600				
material		LIVIE-0000				
Lead frame material	HCL-12S	LY80				
MSL level	MSL 1	MSL 3				

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying GTBF as a new assembly site. CARM assembly site will no longer have manufacturing support the selected TC2117 Catalog Part Numbers (CPN).



Change Implementation Status:

In Progress

Estimated First Ship Date:

November 24, 2019 (date code: 1948)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and

post change parts.

Time Table Summary:

	August 2018			<u> </u>	0010001 2010				November 2019						
Workweek	31	32	33	34	35	디 � 용영 텔	40	41	42	43	44	45	46	47	48
Initial PCN Issue Date		Χ													
Qual Report Availability										Χ					
Final PCN Issue Date										Χ					
Estimated Implementation Date															Χ

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

August 09, 2018: Issued initial notification.

March 05, 2019: Revised the initial notification to include the MSL change from MSL 1 to MSL 3 and revised the qual completion date.

October 24, 2019: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on November 24, 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN KSRA-02YULJ618 Qual Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

TC2117-1.8VEB

TC2117-1.8VEBTR

TC2117-2.5VEB

TC2117-2.5VEBTR

TC2117-3.0VEB

TC2117-3.0VEBTR

TC2117-3.3VEB

TC2117-3.3VEBTR

Date: Wednesday, October 23, 2019